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OCT 11 2006

Customer No.: 31561
Docket No.: 11579-US-PA
Application No.: 10/710,419

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: MAI, Anh D.

Group Art Unit: 2814

In re PATENT APPLICATION of
Applicants : HUANG, Min-Lung

Serial No. : 10/710,419

Filed : July 9, 2004

For : Wafer Structure And Bumping
Process Thereof

AMENDMENT

Attorney Docket: 11579-US-PA

The Commissioner is authorized to charge any fees required in connection with the
filing of this paper to account No. 50-2620 (Order No.: 11579-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office
Customer Service Window
Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Dear Sir:

The Office Action dated July 14, 2006, has been carefully considered. In response thereto,
please enter the following amendments and consider the following remarks.